

10/750,348

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	(10/025304).CCLS.	USPAT	OR	OFF	2005/06/27 10:41
L2	1	10/025304	USPAT	OR	ON	2005/06/27 10:43
L3	1	"6528884".PN.	USPAT; USOCR	OR	ON	2005/06/27 10:42
L4	1	"6482755".PN.	USPAT; USOCR	OR	ON	2005/06/27 10:42
L5	1	"6436824".PN.	USPAT; USOCR	OR	ON	2005/06/27 10:42
L6	1	("6713386").PN.	USPAT	OR	OFF	2005/06/27 10:43
L7	1	6 and (etching or etch or aperture or via or trench or opening or dual or damascene or poison or barrier or pattern or patterned or mask or low-k od dielectric or shares or fiist or second or pH or copper nitrogen or silicon or carbide or copper or oixde or rich or surface or wet or chmical or cvd or cnp or polishing)	USPAT	OR	ON	2005/06/27 10:49
L8	1	2 and (etching or etch or aperture or via or trench or opening or dual or damascene or poison or barrier or pattern or patterned or mask or low-k od dielectric or shares or fiist or second or pH or copper nitrogen or silicon or carbide or copper or oixde or rich or surface or wet or chmical or cvd or cnp or polishing)	USPAT	OR	ON	2005/06/27 10:49
L9	1	3 and (etching or etch or aperture or via or trench or opening or dual or damascene or poison or barrier or pattern or patterned or mask or low-k od dielectric or shares or fiist or second or pH or copper nitrogen or silicon or carbide or copper or oixde or rich or surface or wet or chmical or cvd or cnp or polishing)	USPAT	OR	ON	2005/06/27 10:52
L10	1	4 and (etching or etch or aperture or via or trench or opening or dual or damascene or poison or barrier or pattern or patterned or mask or low-k od dielectric or shares or fiist or second or pH or copper nitrogen or silicon or carbide or copper or oixde or rich or surface or wet or chmical or cvd or cnp or polishing)	USPAT	OR	ON	2005/06/27 10:53

L11	1	5 and (etching or etch or aperture or via or trench or opening or dual or damascene or poison or barrier or pattern or patterned or mask or low-k od dielectric or shares or fiist or second or pH or copper nitrogen or silicon or carbide or copper or oixde or rich or surface or wet or chmical or cvd or cnp or polishing)	USPAT	OR	ON	2005/06/27 11:00
L12	3200	438/637	USPAT	OR	ON	2005/06/27 11:00
L13	1512	438/700	USPAT	OR	ON	2005/06/27 11:00
L14	987	438/639	USPAT	OR	ON	2005/06/27 11:00
L15	1180	438/680	USPAT	OR	ON	2005/06/27 11:01
L16	681	438/697	USPAT	OR	ON	2005/06/27 11:01
L17	1219	438/689	USPAT	OR	ON	2005/06/27 11:01
L18	3492	438/692	USPAT	OR	ON	2005/06/27 11:01
L19	1219	438/689	USPAT	OR	ON	2005/06/27 11:01
L20	892	438/690	USPAT	OR	ON	2005/06/27 11:01
L21	1449	438/691	USPAT	OR	ON	2005/06/27 11:01
L22	1345	438/694	USPAT	OR	ON	2005/06/27 11:01
L23	584	438/695	USPAT	OR	ON	2005/06/27 11:01
L24	595	438/696	USPAT	OR	ON	2005/06/27 11:02
L25	529	438/701	USPAT	OR	ON	2005/06/27 11:02
L26	618	438/702	USPAT	OR	ON	2005/06/27 11:02
L27	408	438/703	USPAT	OR	ON	2005/06/27 11:02
L28	530	438/704	USPAT	OR	ON	2005/06/27 11:02
L29	386	438/705	USPAT	OR	ON	2005/06/27 11:02
L30	1963	438/706	USPAT	OR	ON	2005/06/27 11:02
L31	241	438/931	USPAT	OR	ON	2005/06/27 11:02
L32	1199	438/758	USPAT	OR	ON	2005/06/27 11:02
L33	563	438/740	USPAT	OR	ON	2005/06/27 11:02